13th IEEE CPMT Symposium Japan (ICSJ2024)

The Leading International Components, Packaging and Manufacturing Technology Symposium

November 13-15, 2024
Ritsumeikan University's Suzaku Campus, Kyoto, Japan

Advanced Program (Last update: October 23, 2024)

November 13, 2024 (Wednesday)

Time	4F/5F Main Hall I	No.	1F Room I	No.	1F Room II	No.
9:00			*Registration*			
10:10	*Opening Remark (General Chair, Eiji Higurashi)*					
10:25	*Guest speech (President of Ritsumeikan University, Yoshio Nakatani)*					
10:35	*Award Ceremony*					
10:50-12:30	**Plenary Speech I & II** **Hall I** **Hideyuki Nasu (Furukawa Electric Co., Ltd) and Takaaki Ishigure (Keio University)**					
10:50	**Plenary Speech I: Silicon Photonic MEMS Switch for AI Super Computers** ***Ming Wu (University of California, Berkley)***					P-02
11:40	**Plenary Speech II: Silicon Photonics Light Engines with 2.5/3D Heterogeneous Integration** ***Radhakrishnan Nagarajan (Marvell Technology)***					P-03
12:40-12:55			*Platinum Sponsors' Seminar 1 (with a light meal) @Meetiing Room 1* *OKUNO CHEMICAL INDUSTRIES CO., LTD.*			
12:50-13:05			*Platinum Sponsors' Seminar 2 (with a light meal) @Meetiing Room 1* *Vanguard Automation GmbH*			
13:30-15:25	**Session 1: Photonics I (Active Optical Device)** **Chairperson** **Nobuo Ohata (Mitsubishi Electric Corporation)** **Motohito Takezaki (Hakusan Inc.)**		**Session 2: Process and Material Technologies I** **Chairperson** **Satomi Kawamoto (NAMICS Corporation)** **Kei Murayama (Shinko Electric Industries Co., Ltd.)**		**Session 3: High-Speed Package and System** **Chairperson** **Kazuyuki Nakagawa (Renesas Electronics Corporation)** **Ryo Sakamaki (AIST)**	
13:30	3.2T Co-Package Optics (CPO) Module Based on 200G/ch Silicon-Organic-Hybrid (SOH) *Chin-Ta Chen, Kao-Feng Tsai* *Centera Photonics Inc.*	01-01	Fluxless Low-Temperature Flip Chip Solder Interconnect for Cost Reduction *Teck Kheng Lee Teck Kheng Lee, Kelvin Zheng Kelvin Zheng, Kyu Sik Shim Kyu Sik Shim* *Institute of Technical Education*	02-01	Signal Integrity Analysis and Design for HBM3 on Silicon-Based 2.5D Packaging *Li-Chieh Hung, Cheng-Yu Tsai, Hung-Chun Kuo, Ming-Fong Jhong, Chen-Chao Wang* *ASE*	03-01
13:55	An Ultra-Compact 106-Gb/s PAM4 x 8-Channel Linear-Drive VCSEL-Based Transceiver for Co-Packaged Optics *Wataru Yoshida, Kazuya Nagashima, Kensho Nishizaki, Hideyuki Nasu* *Furukawa Electric Co., Ltd.*	01-02	Al wiring and Cu wiring connection by newly established AL ribbon stack bonding technology for Power package and module *Noriko Numata, Takashi Aoki, Koichi Hasegawa, Manabu Nejiki, Ken Yamamura, Kazuyuki Nakagawa* *Renesas Electronics Corporation*	02-02	High Density, High Bandwidth Copper Interconnects to Support High Density IC Packaging *Kevin Burt, Steve Krooswyk, Andy Shrout, Jignesh Shah, Akinori Mizumura, Chad Faith* *Samtec, Inc*	03-02
14:20	Over 25-GHz Bandwidth Testing Station using a 0.3-mm-Pitch LGA Interface for a 50-Gbaud x 16-channel CPO Transceiver *Kensho Nishizaki, Kazuya Nagashima, Wataru Yoshida, Hideyuki Nasu* *Furukawa Electric Co., Ltd.*	01-03	Enhancing Adhesion and Peel strength for fine line design on FCCSP Package *Rick Yeh, MJ HE, Yu-Cheng Pai, Carl Chen, Yu-Po Wang* *SPIL*	02-03	A Study on Reducing Crosstalk by Efficiently Placing Guard Vias *Msasahiro Yao, Norio Chujo* *Hitachi, Ltd.*	03-03
14:45	Design of Thin-film Narrowband Retroreflector for Oblique Incidence of Diverging Wave *Keisuke Sakatani, Yuya Yamanishi, Keisuke Ozawa, Junichi Inoue, Shogo Ura* *Kyoto Institute of Technology*	01-04	Comparative studies on the reliability and intermetallic integrity of novel Au-coated Ag versus Cu and Au bonding wires *Randolph Flauta, Jorex Lumanog, Suqin Huang, Joe Zhou, King Man Tai, Moon Chen* *Nexperia Group*	02-04	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*	
15:10			*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*			
15:25			*Coffee break + Sponsor's Exhibition*			
15:40-17:35	**Session 4: Photonics II (Optical Fiber and Connector)** **Chairperson** **Hidetoshi Numata (IBM Research - Tokyo)** **Junichi Inoue (Kyoto Institute of Technology)**		**Session 5: Process and Material Technologies II** **Chairperson** **Satomi Kawamoto (NAMICS Corporation)** **Naoko Araki (DAICEL CORPORATION)**		**Session 6: mmWave AiP EMC Package and Systems** **Chairperson** **Yoichiro Kurita (Tokyo Institute of Technology)** **Wataru Shiroi (Renesas Electronics Corporation)**	
15:40	Bend-optimized Optical Fiber with Low Multi-path Interference in the O-band *Scott Bickham, Riley Freeland, Garth Scannell, Stephen Smith, Snigdharaj Mishra, Martin Hempstead, Madison Shipman* *Corning Research and Development Corporation*	04-01	**(Invited)** Thermally Stable Dry-Film Solder Resist for High Temperature Applications *Daisuke Shibata* *Taiyo Ink Mfg. Co. Ltd.*	05-01	Heat Dissipation Study of Sub-THz Band AiP Module *Makoto Tsukahara[1], Kei Murayama[1], Hiroko Ota[1], Hiroshi Taneda[1], Yoichi Nakagawa[2]* *1) Shinko Electric Industries Co., Ltd.* *2) Panasonic Industry Co., Ltd.*	06-01
16:05	Evaluation of MPI suppression by bending a short PMF cable attached to an ELS module *Noe Ishizuka, Daiki Takeda, Tsunetoshi Saito, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	04-02	Five sided protection of the chip with Bump support film impact resistance *Reina Kainuma, Rikiya Kobashi, Keisuke Shinomiya, Takuo Nishida* *LINTEC Corporation*	05-02	Evaluation of Transmission Line Properties on Si-CMOS chip by Probe Backside Reflection Method in Millimeter-Wave Frequencies *Ryo Sakamaki[1], Seitaro Kon[1], Ichiro Somada[2], Takeshi Yoshida[3], Shuhei Amakawa[3], Minoru Fujishima[3]* *1) AIST* *2) Mitsubishi Electric Corporation* *3) Hiroshima University*	06-02
16:30	Quantum co-packaged optical assembly *Bernard Lee[1], Yang Chen[1], R.Ryan Vallance[1], Michael O'Farrel[1], Abu Bakar Bhatti[1], Richard Pitwon[2]* *1) Senko Advanced Components* *2) Resolute Photonics*	04-03	Study on the Novel Fabrication Procedure of Polyimide Multilayer Circuits for a Space Transformer of DRAM Probe Card using Parallel Build-up Process *Seong-Dae Park, Hyunseung Yang, Hyeok Jang* *Korea Electronics Technology Institute*	05-03	Socket Design for 1x4 mmWave AiP with Beamforming Testing *Chia-Ching Chu, Hong-Sheng Huang, Wen-Chun Hsiao, Sheng-Chi Hsieh, Chen-Chao Wang* *ASE, Inc.*	06-03
16:55	Development of Re-assemblable Multifiber Connector for Co-Packaged Optics *Alexander William Setiawan Putra, Kentaro Matsuda, Motohito Takezaki* *Hakusan Inc.*	04-04	A Novel of Ultra Thinner Thermoelectric Device for Wireless Sensor Application *Takuro Yoneda[1], Kosuke Watanabe[2], Koji Miyazaki[2], Kunihisa Kato[1]* *1) Lintec Corporation* *2) Kyushu University*	05-04	High Reliability Solutions of EMI Shielding Technology for Advanced SiP Module *Mike Tsai, Ryan Chiu, James Lin, Ming-fan Tsai, Eddie Zheng, Dave Chen, Tim Chang, Nicholas Kao, J.Y. Chen, Yu-Po Wang* *SPIL*	06-04
17:20			*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*			
17:35-18:15	**Special Speech I** **Hall I** **Chairperson Takaaki Ishigure (Keio University) and Hideyuki Nawata (Nissan Chemical Corporation)**					
17:35	**Special Speech I: Wafer-scale packaging of photonic switches and transceivers** ***Geert Van Steenberge (imec and Ghent University)***					S-05
19:15			*Welcome Reception*			
21:15			*Close*			

November 14, 2024 (Thursday)

Time	4F/5F Main Hall I		1F Room I		1F Room II	
9:00	*Registration*					
9:20-10:10	**Plenary Speech III** **Hall I** **Chairperson Shoji Uegaki (Crane Research) and Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.)**					
9:20	**Plenary Speech III : Advance Heterogeneous Integration package solution for Silicon Photonics application** ***Scott Chen (Advanced Semiconductor Engineering, Inc.)***					P-01
10:10-11:00	**Plenary Speech IV** **Hall I** **Chairperson TBD**					
10:10	**Plenary Speech IV : Chiplet and Advanced Packaging Research Ecosystem** ***John Knickerbocker (IBM)***					P-04
11:00	*Coffee break + Sponsor's Exhibition*					
11:10-12:40	**Session 7: Advanced PKG I** **Chairperson** **Taiji Sakai (TSMC Japan 3DIC R&D Center, Inc.)** **Chinami Marushima (IBM Japan, Ltd.)**		**Session 8: Process and Material Technologies III** **Chairperson** **Shinya Takyu (LINTEC Corporation)** **Naoko Araki (DAICEL CORPORATION)**		**Session 9: Bio electronics I** **Chairperson** **Beomjoon Kim (University of Tokyo)** **Takafumi Fukushima (Tohoku University)**	
11:10	**(Invited)** In-line SEM Evaluation Technique for Cu Pad Nanotopography for Hybrid Bonding Applications *Hiroaki Kasai* *Hitachi High-Tech Corporation*	07-01	**(Invited)** Polymer Optical Waveguide for Silicone Photonics *Nobuyuki Otozawa* *AGC Inc.*	08-01	**(Invited)** Wearable Electronic Packaging Technology for VR and Biomedical Applications *Seiichi Takamatsu* *The University of Tokyo*	09-01
11:35	Oxide microtubes fabrication with 10µm to 5µm pitches and assembly characterization *Natacha Raphoz, Olivier Mailliart, Patrick Peray, Cloe Desbordes, Frederic Berger, Alain Gueugnot* *CEA-LETI*	07-02	New PFAS-free optical adhesive with high heat resistance and low refractive index *Masashi Kajiwara, Yoshito Yamada, Takashi Yamaguchi, Noriyuki Sakai* *NAMICS Corporation*	08-02	**(Invited)** Wood Nanocellulose-Based Green Electronics *Hirotaka Koga* *Osaka University*	09-02
12:00	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		Verification of dicing method for Silicon Photonic wafers *Haruki Otaka, Kazuhiro Yoshida, Tomoharu Fujii* *Shinko Electric Industries Co., Ltd.*	08-03	Failure of PCBs Used as Edge-Card Connectors for Surgical Endoscopes *Kshitij Jayantilal Bopalkar, Viraj Patwardhan, Anthony Okello, Adi Chola Venkatesh* *Vision Engineering Intuitive*	09-03
12:25	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
12:50-13:05			*Platinum Sponsors' Seminar 3 (with a light meal) @Meetiing Room 1* *SENKO Advance Co., Ltd.*			
13:05-13:20			*Platinum Sponsors' Seminar 4 (with a light meal) @Meetiing Room 1* *SURUGA SEIKI CO., LTD.*			
13:45-15:40	**Session 10: Hybrid bonding** **Chairperson** **Takafumi Fukushima (Tohoku University)** **Kenji Takahashi (AIST)**		**Session 11: Photonics III (Photonics Packaging)** **Chairperson** **Hidetoshi Numata (IBM Research - Tokyo)** **Richard C. Pitwon(Resolute Photonics Ltd.)**		**Session 12: Bio electronics II** **Chairperson** **Shigenori Aoki (LINTEC Corporation)** **Kai Takeuchi (Tohoku University)**	
13:45	**(Invited)** Hybrid Bonding in Advanced Heterogenous Integration: Key Metrology Enablers *Bongsub Lee* *Adeia Inc.*	10-01	Ultra High Optical Output Power 8-channel ELS Module Employing a Blind Mate Optical Connector for Co-Packaged Optics *Yuki Shiroishi, Taketsugu Sawamura, Kohei Umeta, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	11-01	Diagnosing PCB(A) deficiencies in medical instruments during reprocessing and sterilization cycles *Toshak Singhal, Viraj Patwardhan* *Intuitive Surgical Inc*	12-01
14:10	**(Invited)** Fine pitch die-to-wafer hybrid bonding integration *Ye Lin* *imec*	10-02	High-Bandwidth Optical Transmission with Single External Laser Source (ELS) and Polymer Splitters for Co-packaged Optics *Satoshi Suda, Md Omar Faruk Rasel, Takayuki Kurosu, Akihiro Noriki, Tadashi Murao, Takeru Amano* *AIST*	11-02	Development of optical microneedle lens array to deliver light efficiently for photodynamic therapy to treat basal cell carcinoma *Anthony Lefebvre[1], Wataru Hanamoto[1], Jongho Park[1], Anne-Sophie Dewalle-Vignion[2], Guillaume Paul Grolez[2], Nadira Delhem[2], Laurent Mortier[2], Beomjoon Kim[1]* *1) The University of Tokyo* *2) Univ. Lille*	12-02
14:35	**(Invited)** Next-Generation Wafer-to-Wafer Bonding Technologies for Sub-50nm Bonding Overlay Accuracy *Tomohiro Chiba* *Nikon Corporation*	10-03	Co-Design of Photonic IC, Electronic IC, and Interposer for 1.6 Tbps O/E Converter in Active Optical Package *Naoki Matsui[1], Akihiro Noriki[2], Haruhiko Kuwatsuka[2], Fumi Nakamura[2], Satoshi Suda[2], Takayuki Kurosu[2], Takeru Amano[2], Satoshi Ishikawa[1], Hiromichi Yoshikawa[1], Dan Maeda[1], Tomoya Sugita[1], Hirotaka Uemura[1]* *1) KYOCERA Corporation* *2) AIST*	11-03	Simulation and Fabrication of Highly Bendable Advanced 3D Corrugated Interconnects Using Flexible FOWLP *HAN ZHANG, Jiayi Shen, Chang Liu, Tetsu Tanaka, Takafumi Fukushima* *Tohoku University*	12-03
15:00	**(Invited)** CMOS Directly Bonded to Array (CBA) Technology for Future 3D Flash Memory *Masayoshi Tagami* *Kioxia Corporation*	10-04	Fabrication of a glass sub-mount with high heat dissipation *Takuma Fujita, Asami Uchiyama, Shinya Okuda, Mizuki Shirao, Nobuo Ohata* *Mitsubishi Electric Corporation*	11-04	Multichip-to-Wafer Mini-LED Bonding Technology for Photobiomodulation Sheet Devices Using Flexible FOWLP *Xingyao Guo, Jiayi Shen, Chang Liu, Tetsu Tanaka, Takafumi Fukushima* *Tohoku University*	12-04
15:25	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
15:40	*Coffee break + Sponsor's Exhibition*					
15:50-16:30	**IEEE EPS Special Speech I** **Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)**					
15:50	**IEEE EPS Special Speech I: Technologies for Chiplet based System Integration** ***Tanja Braun (Fraunhofer IZM)***					S-01
16:30-17:10	**IEEE EPS Special Speech II** **Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) and Eiji Higurashi (Tohoku University)**					
16:30	**IEEE EPS Special Speech II: Mechanical Behavior of Solder Micro Bumps in Advanced Packaging for Heterogeneous Integration** ***Jeffrey Suhling (Auburn University)***					S-02
17:15-18:15	**Early Career Researcher's (ECR) Session (Open Forum with Beer) @ 1F Room I** **Chairperson TBD** Poster presentation					
	Multi-channel Integration of Polymer Spot Size Expander on Silicon Photonics Chip *Atsuki Sawada[1], Yoshiki Kamiura[2], Chiemi Fujikawa[1], Osamu Mikami[3]* *1) Tokai University, 2) Kyushu University* *3) Universiti Teknologi Malaysia*	ECR01	Formation of Au hollow micro-bump arrays for low temperature Au-Au bonding *Shintaro Goto[1], Kai Takeuchi[1], Le Hac Huong Thu[2], Takashi Matsumae[2], Hideki Takagi[2], Yuichi Kurashima[2], Eiji Higurashi[1]* *1) Tohoku University* *2) AIST*	ECR02	Development of Through Semiconductor Via manufacturing process for heterogeneous integration of GaN power device on Si-LSI *Hidejiro Mishima, Kaiyuan Zheng, Satoshi Matsumoto, Satoko Shinkai* *Kyushu Institute of Technology*	ECR-03
	Direct Connection of Multimode Polymer Waveguide and Multimode Fibers Using the Mosquito Method *Tatsuya Nakamura, Takaaki Ishigure* *Keio University*	ECR04	Structural investigation of microchannel and optical waveguide co-integrated sensor devices *Tomohiro Ichizuka, Takaaki Ishigure* *Keio University*	ECR05	Field size converter for edge coupling of multimode LD to thin film waveguide *Yuya Yamanishi[1], Junichi Inoue[1], Keisuke Ozawa[1], Kenji Kintaka[2], Kouki Ichihashi[3], Ura Shogo[1]* *1) Kyoto Institute of Technology* *2) National Institute of Advanced Industrial Science and Technology* *3) Panasonic Holdings Corp.*	ECR-06
	Feasibility Study of Self Assembly Using Copper Nano Film Formed by Blue Laser for Die-to-Wafer Hybrid Bonding *Hayami Asahara, Kiyokazu Yasuda* *Osaka University*	ECR07	3D Polymer Optical Waveguide-based Fan-in/out Device for Silicon Photonics *Anzu Ito, Takaaki Ishigure* *Keio University*	ECR08	Fixed connection of single-mode polymer optical waveguide with single-mode optical fiber *Shunsuke Toshida, Takaaki Ishigure* *Keio University*	ECR-09
	Sequential surface treatment process with VUV light and Ar plasma for room temperature Au-Au bonding *Mika Ogino, Kai Takeuchi, Eiji Higurashi* *Tohoku University*	ECR10	Adhesion between Si Substrates in Liquid Water using Inorganic Polymer *Daiki Nemoto, Kai Takeuchi, Eiji Higurashi* *Tohoku University*	ECR-11		
18:15	*Close*					

November 15, 2024 (Friday)

Time	4F/5F Main Hall I		1F Room I		1F Room II	
9:00	*Registration*					
9:20	*ECR Award Ceremony*					
9:30-10:10	**Special Speech II** **Hall I** **Chairperson TBD**					
9:30	**Special Speech II: Innovation and steps in hetero-integration** ***Harald Kuhn (Fraunhofer ENAS)***					S-03
10:10-10:50	**Special Speech III** **Hall I** **Chairperson Kraisorn Throngnumchai (Kanagawa Institute of Technology) and Yutaka Uematsu (Hitachi, Ltd.)**					
10:10	**Special Speech III: Wireless Power Transfer Theory Established Last Decade** ***Takashi Ohira (Toyohashi University of Technology)***					S-04
10:50	*Coffee break + Sponsor's Exhibition*					
11:00-12:30	**Session 13: IEEE EPS Technical session Glass Substrate** **Chairperson** **Shigenori Aoki (LINTEC Corporation)** **Takashi Hisada (Rapidus)**		**Session 14: Advanced Automotive Electronics** **Chairperson** **Atsushi Nakamura (Ultimate Technologies Inc.)** **Yutaka Uematsu (Hitachi, Ltd.)**		**Session 15: Advanced PKG II** **Chairperson** **Kiyokazu Yasuda (Osaka University)** **Shoji Uegaki (Crane Research)**	
11:00	**(Invited)** Advanced Materials and Processes for Glass-core Packaging *Mohan Kathaperumal* *Georgia Institute of Technology*	13-01	**(Invited)** Application of EMC Simulation Including Semiconductor to Reduce Development Lead Time *Kazuki Furukawa* *AISIN Corporation*	14-01	Novel Additive Manufacturing Platform for Freeform 3D Microelectronics and Packaging *Darragh Walsh, Jeroen Sol, Hylke Akkerman* *Holst Centre/TNO*	15-01
11:25	**(Invited)** Glass materials and glass structuring technologies for glass-core substrates *Yoichiro Sato* *AGC Inc.*	13-02	Compact Design for Automotive High-Performance Computing Using a Two-Layer Daughter Board Structure *Soshi Shimomura, Masako Kato, Yutaka Uematsu* *Hitachi, Ltd.*	14-02	Effect of Microstructure on the Electromigration Performance of 2-μm-Cu Redistribution Line under In-situ SEM Observation *Min-Yan Tsai, Ting-Chun Lin, Yen-Cheng Huang, Shan-Bo Wang, Yung-Sheng Lin, Kwang-Lung Lin* *ASE Group*	15-02
11:50	**(Invited)** Reliability Assessment of Glass Substrate/Interposer *SB Park* *Binghamton University*	13-03	Efficient German License Plate Recognition System Integrating YOLOv8 Model and EasyOCR *Hasan Aljzaere, Atul Chandra Nath, Wolfram Hardt* *Chemnitz University of Technology*	14-03	Implementation of Curved CMOS Image Sensors by Transferring Silicon-On-Insulator Layers *Masahide Goto, Shigeyuki Imura, Hiroto Sato* *NHK Science & Technology Research Laboratories*	15-03
12:15	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
12:30-14:00	*Lunch (free time)*					
14:00-16:20	**Session 16: Photonics IV (Laser, Process and Polymer technologies for Photonics)** **Chairperson** **Hideyuki Nasu (Furukawa Electric Co., Ltd.)** **Motohito Takezaki (Hakusan Inc.)**		**Session 17: EMC and Automotive PKG** **Chairperson** **Yutaka Uematsu (Hitachi, Ltd.)** **Atsushi Nakamura (Ultimate Technologies Inc.)**		**Session 18: Power Electronics Materials and devices of UWBG and WBG semiconductors** **Chairperson** **Kentaro Kaneko (Ritsumeikan University)** **Hiroki Imabayashi (University of Fukui)**	
14:00	Heat Assisted Magnetic Recording - Ultra-dense laser and plasmonic component integration to increase storage density on magnetic media *Mark Gubbins, Beverley McConnell, Michael Kautzy, Anil Reddy, Richard Pitwon* *Seagate Technology*	16-01	**(Invited)** EMC overview, Causes and Physics *Hideho Yamamura* *Ultimate Technologies Inc.*	17-01	**(Invited)** Recent progress and task of GaN materials and devices for power applications *Yohei Otoki* *SCIOCS Co. Ltd.*	18-01
14:25	Polarization dependent characteristics of polymer optical waveguide *Takumi Wakabayashi, Takaaki Ishigure* *Keio University*	16-02	A Review of BMW iX3 Power Module – Part 1: Inner Configuration, Die Attachment, Busbar Connection and Molding *Thiyu Warnakulasooriya, Jiyoon Choi, Sihoon Choi, Jun Imaoka, Masayoshi Yamamoto* *Nagoya University*	17-02	Ag Sintering based Die Attach for Power Package and Power Module Applications *Tamimoto Hideaki Tamimoto Hideaki, Kazuki Matsumura, Kazuyuki Nakagawa, Kenji Ikura, Chikara Obama* *Renesas Electronics Corporation*	18-02
14:50	Loss reduction of Y-branched single-mode polymer optical waveguide for MUX/DEMUX devices in mode division multiplexing links. *Seiya Sakai, Takaaki Ishigure* *Keio University*	16-03	A Review of BMW iX3 Power Module – Part 2: Novel Heatsink Structure, Stacked-plate Fin Configuration *Jiyoon Choi, Thiyu Warnakulasooriya, Sihoon Choi, Jun Imaoka, Masayoshi Yamamoto* *Nagoya University*	17-03	Simulation Study of Factor Effect on Transient Thermal Ramp Up Test Performance for Electronic Power Devices *Nick Chenchao Zhong, Haibo Fan, Yuning Shi* *Nexperia Group*	18-03
15:15	Towards scalable aligned two photon lithography for photonic integration *Mareike Trappen, Matthias Blaicher, Tobias Hoose, Nicole Lindenmann, Stephan Dottermusch, Benjamin Richter, Andrea Bertoncini, Michael Thiel* *Nanoscribe GmbH & Co. KG*	16-04	High-Performance Flip-Chip BGA Packages Reliability Prediction in Automotive Applications *Bo-Heng Chen, Wei-Hong Lai, Chin-Li Kao, Alexcc Wang, CP Hung* *ASE Inc.*	17-04	Effect of Sb dopant in r-GeO2 thin films for high-temperature growth *Toya Yagura[1,2], Yuri Shimizu[2], Toyosuke Ibi[1], Isao Takahashi[1], Kentaro Kaneko[1,2]* *1) Patentix Inc.* *2) Ritsumeikan Univ.*	18-04
15:40	Post-fab laser trimming: increasing yield and lowering power consumption of PICs *Ignazio Piacentini[1], Louis-Rafael Robichaud[2], Simon Duval[2]* *1) IP Consulting* *2) Femtum Inc.*	16-05	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*			
16:05	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
16:20	*Close*					